



PATENT
Customer No. 22,852
Attorney Docket No. 04329.2619

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Takahito NAKAZAWA et al.

Application No.: 09/920,628

Filed: 08/03/2001

For: CHIP PICKUP DEVICE AND
METHOD OF MANUFACTURING
SEMICONDUCTOR DEVICE

Group Art Unit: 2827

Examiner: Zarneke, D.

Commissioner for Patents
Washington, DC 20231

Sir:

RESPONSE TO RESTRICTION REQUIREMENT AND AMENDMENT

In response to the Office Action dated July 22, 2002, Applicants submit the following amendment and remarks. This response is due by October 22, 2002 and is timely filed.

IN THE CLAIMS:

Please amend claim 13 as follows:

13. (Amended) A method of manufacturing a semiconductor device, comprising:
- adhering on an adhesive side of an adhesive tape chips separated by dicing a wafer; and
- repeating a step of peeling a chip off the adhesive tape to sequentially peel the chips off the adhesive tape, wherein the step of peeling a chip off the adhesive tape comprises:

#6/A
J. McInnis
10/28/02

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